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**Screen Launches Single Wafer Cleaning System
Capable of Handling Ultra-thin Substrate Wafers**
— *Supports Production of Semiconductor Sensors Used in Smartphone Cameras
and Power Devices for Hybrid Vehicles* —

Kyoto, Japan – November 28, 2012 – Dainippon Screen Mfg. Co., Ltd. today announced that it will release its new SU-2000 single wafer cleaning system in December 2012. The SU-2000 supports the production of CMOS backside illumination (BSI) sensors for smartphone cameras, currently experiencing rapidly increasing demand, and the power devices that are essential for the electronic control of hybrid and electric vehicles, as well as solar generation and other renewable energy systems. Screen intends to further expand its lineup of equipment for the semiconductor sensor and power device fields, markets in which continuing growth is strongly anticipated.



SU-2000

Please download the photo from
www.screen.co.jp/eng/press/nr-photo_2012-2013.html

Date sales are expected to commence:	December 5, 2012
Expected annual sales:	15 systems

In recent years, increasing miniaturization and higher resolutions have both been sought in the field producing the imaging sensors for the cameras used in smartphones and tablet PCs. CMOS BSI imaging sensors, designed to directly receive light on the rear side of elements, have been attracting particular attention. At the same time, demand has expanded rapidly for the power devices used in the inverters that efficiently control the electrical supply for hybrid and electric vehicles, along with solar generation and other renewable energy systems.

As it has become increasingly necessary to handle ultra-thin wafers in the manufacturing processes for these types of semiconductor elements, there has also been an urgent need to develop similar capabilities for cleaning processes. In addition, due to the wide-scale usage of conventional manufacturing lines for the mass production of these elements, there is a strong requirement for compact, high-throughput single wafer cleaning systems that can be substituted into or added to these lines.

In response to these industry trends, Screen has developed the SU-2000 single wafer cleaning system as part of its Frontier Project, which has been established to promote the opening up of new fields in the semiconductor

manufacturing equipment business. The SU-2000 utilizes cleaning technology and knowhow inherited from Screen's SU-3200 flagship model and is also equipped with cleaning systems capable of handling ultra-thin substrate wafers. In addition, while delivering space savings and greater cost performance, it is also able to flexibly accommodate increasing miniaturization of circuit patterns and new production techniques. In short, the SU-2000 is a system that solves many of the different problems faced by the semiconductor industry.

Screen has developed the SU-2000 as the fourth stage of its Frontier Project and its release will enhance the lineup of products targeting new fields. As well as further expanding business areas, it will contribute to the continuing overall growth of the semiconductor industry.

Note: This system will be exhibited at SEMICON Japan 2012, held from Wednesday, December 5 to Friday, December 7 at the Makuhari Messe convention complex in Chiba, Japan.